CMOS IC 8K-byte FROM and 256-byte RAM integrated 8-bit 1-chip Microcontroller



Overview

The LC87F2H08A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 8K-byte flash ROM (On-board-programmable), 256-byte RAM, an On-chip-debugger, sophisticated 16-bit timers/counters (may be divided into 8-bit timers), a 16-bit timer/counter (may be divided into 8-bit timers/counters or 8-bit PWMs), two 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface, an asynchronous/synchronous SIO interface, a UART interface (full duplex), two 12-bit PWM channels, a 12/8-bit 9-channel AD converter, a system clock frequency divider, an internal reset and a 20-source 10-vector interrupt feature.

Features

■Flash ROM

- Capable of on-board programming with a wide range (2.2 to 5.5V) of voltage source.
- Block-erasable in 128 byte units
- Writable in 2-byte units
- 8192 × 8 bits

■RAM

• 256×9 bits

■Minimum Bus Cycle

- 83.3ns (12MHz at V_{DD}=2.7V to 5.5V)
- 100ns (10MHz at VDD=2.2V to 5.5V)
- 250ns (4MHz at V_{DD}=1.8V to 5.5V)
- Note: The bus cycle time here refers to the ROM read speed.

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■Minimum Instruction Cycle Time

- 250ns (12MHz at V_{DD}=2.7V to 5.5V)
- 300ns (10MHz at V_{DD}=2.2V to 5.5V)
- 750ns (4MHz at V_{DD}=1.8V to 5.5V)

■Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1-bit units 16 (Pin, P20, P21, P30, P31, P70 to P73)

- Ports whose I/O direction can be designated in 4-bit units
- Dedicated oscillator ports/input ports
- Reset pin
- Power pins
- ■Timers
 - Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) × 2 channels Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)

- + 8-bit counter (with an 8-bit capture register)
- Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
- Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/

- counter with an 8-bit prescaler (with toggle outputs)
- Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels
- Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from the lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)

(The lower-order 8 bits can be used as PWM)

- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts are programmable in 5 different time schemes
- ■High-Speed Clock Counter
 - Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
 - Can generate output real time.

■SIO

- SIO0: 8-bit Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle=4/3tCYC)
- SIO1: 8-bit asynchronous/synchronous serial interface
 Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■UART

- Full Duplex
- 7/8/9 bit data bits selectable
- 1 Stop bit (2 bits in continuous data transmission)
- Built-in baudrate generator

■AD Converter: 12 bits/8 bits × 9 channels

• 12/8 bits AD converter resolution selectable

16 (Pin, P20, P21, P30, P31, P70 to P73) 8 (P0n) 2 (CF1/XT1, CF2/XT2) 1 (RES) 3 (VSS1, VSS2, VDD1)

■PWM: Multifrequency 12-bit PWM × 2 channels

Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)

- Noise rejection function (noise filter time constant selectable from 1 tCYC/32 tCYC/128 tCYC)
- Clock Output Function
 - Can generate clock outputs with a frequency of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 of the source clock selected as the system clock.
 - Can generate the source clock for the subclock

■Watchdog Timer

- External RC watchdog timer
- Interrupt and reset signals selectable

■Interrupts

- 20 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7/PWM4, PWM5
10	0004BH	H or L	Port 0

• Priority levels X > H > L

• Of interrupts of the same level, the one with the smallest vector address takes precedence.

Subroutine Stack Levels: 128levels (The stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits \div 16 bits (12 tCYC execution time)

■Oscillation Circuits

 Internal oscillation circuits 	
Low-speed RC oscillation circuit :	For system clock (100kHz)
Medium-speed RC oscillation circuit :	For system clock (1MHz)
Multifrequency RC oscillation circuit :	For system clock (8MHz)
• External oscillation circuits	
Hi-speed CF oscillation circuit:	For system clock, with internal Rf
Low speed crystal oscillation circuit:	For low-speed system clock, with internal Rf
1) The CF and crystal oscillation circuit	s share the same pins. The active circuit is selected under program control.
2) Both the CF and crystal oscillator circ	cuits stop operation on a system reset. When the reset is released, only the
CF oscillation circuit resumes operati	on.

System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2µs, 2.4µs, 4.8µs, 9.6µs, 19.2µs, 38.4µs, and 76.8µs (at a main clock rate of 10MHz).

■Internal reset function

- Power-on reset (POR) function
 - 1) POR reset is generated only at power-on time.
 - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
- Low-voltage detection reset (LVD) function
 - 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - 2) The use/disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, 4.28V).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
- 1) The CF, RC and crystal oscillators automatically stop operation.
- 2) There are four ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4 or INT5
 - * INT0 and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0.
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The CF and RC oscillator automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are five ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level.
 - (2) System resetting by watchdog timer or low-voltage detection.
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4 or INT5
 - * INT0 and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0.
 - (5) Having an interrupt source established in the base timer circuit.
 - Note: Available only when X'tal oscillation is selected.

Onchip Debugger

- Supports software debugging with the IC mounted on the target board.
- Two channels of on-chip debugger pins are available to be compatible with small pin count devices. DBGP0 (P0), DBGP1 (P1)
- Data Security Function (flash versions only)
 - Protects the program data stored in flash memory from unauthorized read or copy. Note: This data security function does not necessarily provide absolute data security.
- ■Package Form
 - QFP36 (7×7): Lead-free type

■Development Tools

• On-chip debugger: TCB87 type B + LC87F2H08A

■Programming Boards

Package	Programming boards
QFP36(7×7)	W87F24Q

■Flash ROM Programmer

Maker		Model	Supported version	Device	
Flash Support Group, Inc. (FSG)	Single Programmer	AF9708 AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 02.72 or later	LC87F2H08A	
	Gang	AF9723/AF9723B(Main body) (Including Ando Electric Co., Ltd. models)	-	-	
	Programmer	AF9833(Unit) (Including Ando Electric Co., Ltd. models)	-	-	
Flash Support Group, Inc. (FSG)	• •	AF9101/AF9103(Main body) (FSG models)			
+ Our company (Note 1)	Programmer	SIB87(Inter Face Driver) (Our company model)	(Note 2)	LC87F2H08A	
0	Single/Gang Programmer	SKK/SKK Type B (SANYO FWS)	Application Version 1.04 or later		
Our company	In-circuit/Gang Programmer	SKK-DBG Type B (SANYO FWS)	Chip Data Version 2.10 or later	LC87F2H08A	

For information about AF-Series:

Flash Support Group, Inc.

TEL: +81-53-459-1050 E-mail: sales@j-fsg.co.jp

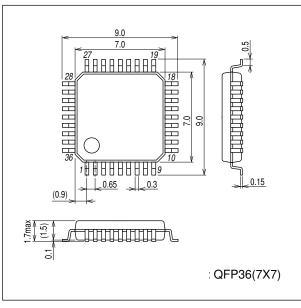
Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together

can give a PC-less, standalone on-board-programming capabilities.

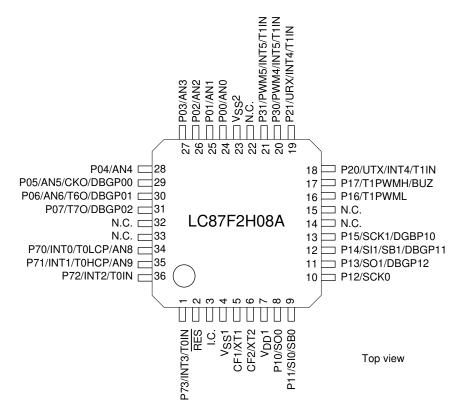
Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.

Package Dimensions

unit : mm (typ) 3162C



Pin Assignment

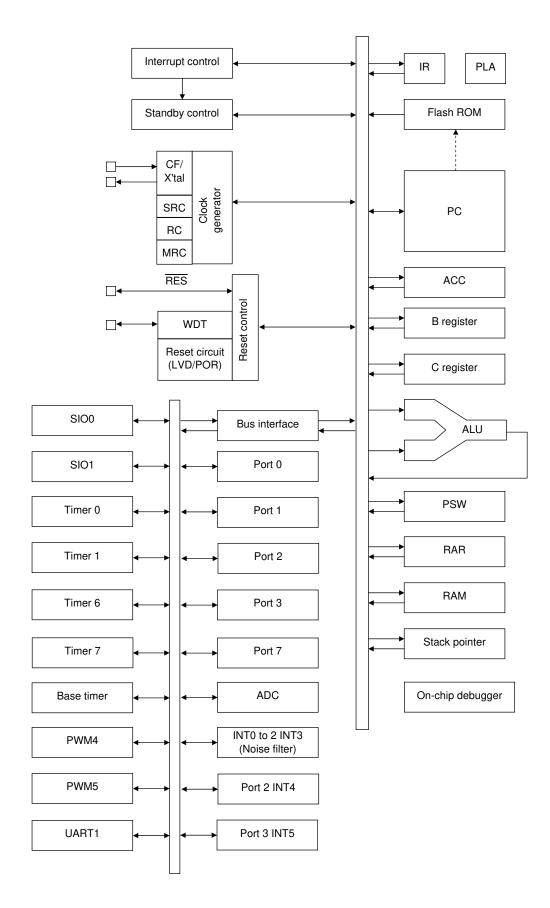


QFP36 (7×7) "Lead-free Type"

QFP36	NAME	QFP36	NAME
1	P73/INT3/T0IN	19	P21/URX/INT4/T1IN
2	RES	20	P30/PWM4/INT5/T1IN
3	I.C.	21	P31/PWM5/INT5/T1IN
4	V _{SS} 1	22	N.C.
5	CF1/XT1	23	V _{SS} 2
6	CF2/XT2	24	P00/AN0
7	V _{DD} 1	25	P01/AN1
8	P10/SO0	26	P02/AN2
9	P11/SI0/SB0	27	P03/AN3
10	P12/SCK0	28	P04/AN4
11	P13/SO1/DBGP12	29	P05/AN5/CKO/DBGP00
12	P14/SI1/SB1/DBGP11	30	P06/AN6/T6O/DBGP01
13	P15/SCK1/DBGP10	31	P07/T7O/DBGP02
14	N.C.	32	N.C.
15	N.C.	33	N.C.
16	P16/T1PWML	34	P70/INT0/T0LCP/AN8
17	P17/T1PWMH/BUZ	35	P71/INT1/T0HCP/AN9
18	P20/UTX/INT4/T1IN	36	P72/INT2/T0IN

Note I.C. and N.C. pins must be held open (disconnected).

System Block Diagram



Pin Description

Pin Name	I/O			De	scription			Option
V _{SS} 1,V _{SS} 2	-	- power supply	power supply pins					No
V _{DD} 1	-	+ power supply	power supply pin					
Port 0 P00 to P07	I/O	 8-bit I/O port I/O specifiable Pull-up resisted HOLD reset in Port 0 interrup Pin functions P05: System of P06: Timer 6 t P07: Timer 7 t P00(AN0) to F 	e in 4-bit units ors can be turned oput ot input clock output oggle output	nverter input				Yes
Port 1 P10 to P17	I/O	Pin functions P10: SIO0 dat P11: SIO0 dat P12: SIO0 clo P13: SIO1 dat	ors can be turned a output a input/bus I/O ck I/O	P14 P15 P10 P17	4: SIO1 data inpu 5: SIO1 clock I/O 6: Timer 1 PWML 7: Timer 1 PWMI	. output	output	Yes
Port 2 P20 to P21	1/0	2-bit I/O port I/O specifiable Pull-up resiste Pin functions P20: UART tra P21: UART re P20 to P21: IN tir Interrupt ackno INT4	in 1-bit units ors can be turned ansmit ceive IT4 input/HOLD mer 0H capture in	d on and off in 1 reset input/time		ner 0L capture H level disable	input/ L level disable	Yes
Port 3 P30 to P31	I/O	Pin functions P30: PWM4 o P31: PWM5 o P30 to P31: IN ti	ors can be turnec utput utput	reset input/time	-bit units. er 1 event input/tii Rising & Falling enable	ner 0L capture H level disable	input/ L level disable	Yes

Continued on next page.

Pin Name	I/O		Description							
Port 7	I/O	• 4-bit I/O port	-bit I/O port							
P70 to P73		 I/O specifiable 	in 1-bit units							
		Pull-up resisto	rs can be turned	on and off in 1-	bit units.					
		Pin functions								
		P70: INT0 inpu	t/HOLD reset in	put/timer 0L cap	ture input/watch	dog timer outpu	t			
		P71: INT1 inpu	t/HOLD reset in	put/timer 0H cap	oture input					
		P72: INT2 inpu	t/HOLD reset in	put/timer 0 even	t input/timer 0L o	capture input				
		P73: INT3 inpu	t (input with nois	se filter)/timer 0	event input/timer	0H capture inp	ut			
		. ,.	P70(AN8),P71(AN9) : AD converter input							
		Interrupt ackno	wledge types	1	1	1		No		
			Rising	Falling	Rising &	H level	L level			
				. cimig	Falling		210701			
		INT0	enable	enable	disable	enable	enable			
		INT1	enable	enable	disable	enable	enable			
		INT2	enable	enable	enable	disable	disable			
		INT3	enable	enable	enable	disable	disable			
						•	<u> </u>			
RES	I/O	External reset In	put/internal rese	t output				No		
CF1/XT1		Ceramic resonator or 32.768kHz crystal oscillator input pin								
	Pin function					No				
		General-purpose input port								
CF2/XT2	I/O	Ceramic reson	ator or 32.768kH	Iz crystal oscilla	tor output pin					
		 Pin function 						No		
	General-purpose input port									

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P31	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable

Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low-and high-impedance pull-up connection is exercised in nibble (4-bit) units (P00 to 03 or P04 to 07).

Note: Be sure to electrically short-circuit between the VSS1 and VSS2 pins.

User Option Table

Option Name	Option to be Applied on	Flash-ROM Version	Option Selected in Units of	Option Selection
Port output type	P00 to P07	0	1 bit	CMOS
				Nch-open drain
	P10 to P17	0	1 bit	CMOS
				Nch-open drain
	P20 to P21	0	1 bit	CMOS
				Nch-open drain
	P30 to P31	0	1 bit	CMOS
				Nch-open drain
Program start	-	0	-	00000h
address				01E00h
Low-voltage	Detect function	0	-	Enable:Use
detection reset				Disable:Not Used
function	Detect level	0	-	7-level
Power-on reset function	Power-On reset level	0	-	8-level

Recommended Unused Pin Connections

Port Name	Recommended Unused F	Pin Connections
Port Name	Board	Software
P00 to P07	Open	Output low
P10 to P17	Open	Output low
P20 to P21	Open	Output low
P30 to P31	Open	Output low
P70 to P73	Open	Output low
CF1/XT1	Pulled low with a 100k Ω resistor or less	General-purpose input port
CF2/XT2	Pulled low with a 100k Ω resistor or less	General-purpose input port

On-chip Debugger pin connection requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 on-chip debugger installation manual" and "LC872000 series on-chip debugger pin connection requirements"

Note: Be sure to electrically short-circuit between the $V_{\mbox{\scriptsize SS}}1$ and $V_{\mbox{\scriptsize SS}}2$ pins.

	Parameter	Symbol	Pin/Remarks	Conditions			Specif	ication	
	1 didifictor	Gymbol	T in/Tiemanio	Conditions	V _{DD} [V]	min	typ	max	unit
	ximum supply tage	V _{DD} max	V _{DD} 1			-0.3		+6.5	
Input voltage Input/output voltage		VI	CF1, CF2			-0.3		V _{DD} +0.3	V
		V _{IO}	Ports 0, 1, 2, 3 Port 7			-0.3		V _{DD} +0.3	
Voltage Peak output current	•	IOPH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-10			
ut		IOPH(2)	P71 to P73	Per 1 applicable pin		-5			
High level output current	Mean output current	IOMH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-7.5			
utpu	(Note 1-1)	IOMH(2)	P71 to P73	Per 1 applicable pin		-3			
vel c	Total output	$\Sigma IOAH(1)$	P71 to P73	Total of all applicable pins		-10			
gh le	current	ΣIOAH(2)	P10 to P14	Total of all applicable pins		-20			
Ξ		ΣIOAH(3)	P15 to P17 Ports 0, 2, 3	Total of all applicable pins		-20			
		ΣIOAH(4)	Ports 0, 1, 2, 3	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2, 3	Per 1 applicable pin				20	m
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Port 7	Per 1 applicable pin				10	
Low level output current	Mean output current	IOML(1)	P02 to P07 Ports 1, 2, 3	Per 1 applicable pin				15	
utput	(Note 1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	
el or		IOML(3)	Port 7	Per 1 applicable pin				7.5	
v lev	Total output	ΣIOAL(1)	Port 7	Total of all applicable pins				15	
Lov	current	ΣIOAL(2)	Port 0	Total of all applicable pins				40	
		ΣIOAL(3)	P10 to P14	Total of all applicable pins				35	
		ΣIOAL(4)	Ports 1, 2, 3	Total of all applicable pins				40	
		ΣIOAL(5)	Ports 0, 1, 2, 3	Total of all applicable pins				70	
	wer sipation	Pd max(1)	QFP36(7×7)	Ta=-40 to +85°C Package only				120	
Dissipation		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				275	m'
	erating ambient mperature	Topr				-40		+85	
Sto	prage ambient	Tstg				-55		+125	°(

Absolute Maximum Ratings at $Ta = 25^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Parameter	Symbol	Pin/Remarks	Conditions		Specification			
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1	$0.245 \mu s \leq tCYC \leq 200 \mu s$		2.7		5.5	
supply voltage	V _{DD} (2)		$0.294 \mu s \leq tCYC \leq 200 \mu s$		2.2		5.5	
(Note 2-1)	V _{DD} (3)		$0.735\mu s \le tCYC \le 200\mu s$		1.8		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1	RAM and register contents sustained in HOLD mode.		1.6			
High level input voltage	V _{IH} (1)	Ports 1, 2, 3, P71 to P73 P70 port input/ interrupt side		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
-	V _{IH} (2)	Ports 0		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (3)	Port 70 watchdog timer side		1.8 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (4)	CF1, RES		1.8 to 5.5	0.75V _{DD}		V _{DD}	
Low level	V _{IL} (1)	Ports 1, 2, 3,		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
input voltage		P71 to P73 P70 port input/ interrupt side		1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (2)	Ports 0		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
				1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 70 watchdog timer side		1.8 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (4)	CF1, RES		1.8 to 5.5	V _{SS}		0.25V _{DD}	
Instruction	tCYC			2.7 to 5.5	0.245		200	
cycle time	(Note 2-2)			2.2 to 5.5	0.294		200	μs
(Note 2-1)				1.8 to 5.5	0.735		200	1
External	FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12	
system clock frequency			 System clock frequency division ratio=1/1 External system clock duty=50±5% 	1.8 to 5.5	0.1		4	
			CF2 pin open	3.0 to 5.5	0.2		24.4	MH
			 System clock frequency division ratio=1/2 External system clock duty=50±5% 	2.0 to 5.5	0.2		8	
Oscillation frequency	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		12		
range (Note 2-3)	FmCF(2)	CF1, CF2	10MHz ceramic oscillation See Fig. 1.	2.2 to 5.5		10		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation. CF oscillation normal amplifier size selected. See Fig. 1. (CFLAMP=0)	1.8 to 5.5		4		
			4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1.	2.2 to 5.5		4		MH
	FmMRC		Frequency variable RC oscillation. 1/2 frequency division ration. (RCCTD=0) (Note 2-4)	2.7 to 5.5	7.44	8.0	8.56	
	FmRC		Internal medium-speed RC oscillation	1.8 to 5.5	0.5	1.0	2.0	
	FmSRC		Internal low-speed RC oscillation	1.8 to 5.5	50	100	200]
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation	1.8 to 5.5		32.768		kHz

Allowable Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

- Note 2-3: See Tables 1 and 2 for the oscillation constants.
- Note 2-4: When switching the system clock, allow an oscillation stabilization time of 100µs or longer after the multifrequency RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3 Port 7 RES	Output disabled Pull-up resistor off V _{IN} =V _{DD} (Including output Tr's off leakage current)	1.8 to 5.5			1	
	I _{IH} (2)	CF1	V _{IN} =V _{DD}	1.8 to 5.5			15	
Low level input current	lη _L (1)	Ports 0, 1, 2, 3 Port 7 RES	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	1.8 to 5.5	-1			μA
	I _{IL} (2)	CF1	V _{IN} =V _{SS}	1.8 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.35mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.15mA	1.8 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	Port 3	I _{OH} =-6mA	4.5 to 5.5	V _{DD} -1			
	V _{OH} (5)		I _{OH} =-1.4mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (6)		I _{OH} =-0.8mA	1.8 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1, 2, 3	I _{OL} =10mA	4.5 to 5.5			1.5	v
voltage	V _{OL} (2)		I _{OL} =1.4mA	2.7 to 5.5			0.4	v
	V _{OL} (3)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (4)	Port 7	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (5)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (6)	P00, P01	I _{OL} =25mA	4.5 to 5.5			1.5	
	V _{OL} (7)		I _{OL} =4mA	2.7 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =2mA	1.8 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	Port 7	When Port 0 selected low-impedance pull-up.	1.8 to 4.5	18	50	230	1.0
	Rpu(3)	Port 0	V _{OH} =0.9V _{DD} When Port 0 selected high-impedance pull-up.	1.8 to 5.5	100	210	400	kΩ
Hysteresis voltage	VHYS(1)	Ports 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		v
	VHYS(2)	RES		1.8 to 2.7		0.07V _{DD}		v
Pin capacitance	CP	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	1.8 to 5.5		10		pF

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

	r	Dexemptor	Cumbal	Pin/	Conditions			Speci	fication	
	1	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(1)			1.8 to 5.5	1			tCYC
Serial clock	dul	High level pulse width	tSCKH(1)				1			
eria	¥	Frequency	tSCK(2)	SCK0(P12)	 CMOS output selected 		4/3			
S	Dutput clock	Low level pulse width	tSCKL(2)		• See Fig. 5.	1.8 to 5.5		1/2		tSCK
	Out	High level pulse width	tSCKH(2)					1/2		ISON
Serial input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	 Must be specified with respect to rising edge of SIOCLK. 	1.8 to 5.5	0.05			
Seri	Da	ta hold time	thDI(1)		• See Fig. 5.		0.05			
	Input clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-2)				(1/3)tCYC +0.08	μs
Serial output	ndul		tdD0(2)		Synchronous 8-bit mode (Note 4-1-2)	1.8 to 5.5			1tCYC +0.08	
Serial	Output clock		tdD0(3)		(Note 4-1-2)	1.010 5.5			(1/3)tCYC +0.08	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		Parameter	Oursehal	Pin/	Oranditions			Spec	ification	
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(3)			1.8 to 5.5	1			
clock	u L	High level	tSCKH(3)				1			tCYC
Serial clock	Š	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig. 5.		2			
	Output clock	Low level pulse width	tSCKL(4)			1.8 to 5.5		1/2		10.014
	no	High level pulse width	tSCKH(4)					1/2		tSCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 5. 		0.05			
Serial	Da	ata hold time	thDI(2)			1.8 to 5.5	0.05			
Serial output	0	utput delay time	tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5. 	1.8 to 5.5			(1/3)tCYC +0.08	μs

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Devenuetar	Oursels al	Dia (De se este	Oraditions			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tPIH(1) tPIL(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P21), INT5(P30 to P31)	 Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled. 	1.8 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	1.8 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	 Interrupt source flag can be set. Event inputs for timer 0 are nabled. 	1.8 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	1.8 to 5.5	256			
	tPIL(5)	RES	 Resetting is enabled. 	1.8 to 5.5	200			μs

AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = 0V$

<12bits AD Converter Mode/Ta = -40° C to $+85^{\circ}$ C >

Parameter	Cumbal	Pin/Remarks	Conditions			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		2.4 to 5.5		12		bit
Absolute	ET	AN6(P06),	(Note 6-1)	3.0 to 5.5			±16	
accuracy		AN8(P70), AN9(P71)	(Note 6-1) ● Ta=-10 to +50°C	2.4 to 3.6			±20	LSB
Conversion time	TCAD		See Conversion time calculation	4.0 to 5.5	32		115	
			formulas. (Note 6-2)	3.0 to 5.5	64		115	
			 See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C 	2.4 to 3.6	410		425	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	v
Analog port	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μA

<8bits AD Converter Mode/Ta = -40° C to $+85^{\circ}$ C >

Demonster	Querrahad	Pin/Remarks	Quaditiana			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		2.4 to 5.5		8		bit
Absolute accuracy	ET	AN6(P06) AN8(P70)	(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion time	TCAD	AN9(P71)	See Conversion time calculation	4.0 to 5.5	20		90	
			formulas. (Note 6-2)	3.0 to 5.5	40		90	
			 See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C 	2.4 to 3.6	250		265	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	V
Analog port	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μA

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time) = $((52/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 8bits AD Converter Mode: TCAD(Conversion time) = $((32/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$

External oscillation	Operating supply voltage range	System division ratio	Cycle time	AD division ratio	AD conversion time (TCAD)		
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD	
	4.0V to 5.5V	1/1	250ns	1/8	34.8µs	21.5µs	
CF-12MHz	3.0V to 5.5V	1/1	250ns	1/16	69.5µs	42.8µs	
	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8µs	
CF-10MHz	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4µs	
	3.0V to 5.5V	1/1	750ns	1/8	104.5µs	64.5µs	
CF-4MHz	2.4V to 3.6V	1/1	750ns	1/32	416.5µs	256.5µs	

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

Power-on Reset (POR) Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1=V_{SS}2=0V$

						Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
POR release	PORRL		Select from option.	1.67V	1.55	1.67	1.79	
voltage			(Note 7-1)	1.97V	1.85	1.97	2.09	
				2.07V	1.95	2.07	2.19	
				2.37V	2.25	2.37	2.49	
				2.57V	2.45	2.57	2.69	
				2.87V	2.75	2.87	2.99	V
				3.86V	3.73	3.86	3.99	
				4.35V	4.21	4.35	4.49	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 7-2)			0.7	0.95	
Power supply rise time	PORIS		• Power supply rise time from 0V to 1.6V.				100	ms

Note7-1: The POR release level can be selected out of 8 levels only when the LVD reset function is disabled. Note7-2: POR is in an unknown state before transistors start operation.

Low Voltage Detection Reset (LVD) Characteristics at Ta = -40°C to +85°C, V_{SS}1=V_{SS}2=0V

						Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
LVD reset Voltage	LVDET		Select from option.	1.91V	1.81	1.91	2.01	
(Note 8-2)			(Note 8-1)	2.01V	1.91	2.01	2.11	
			(Note 8-3) • See Fig. 8.	2.31V	2.21	2.31	2.41	
			• See Fig. 6.	2.51V	2.41	2.51	2.61	V
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD hysteresys	LVHYS			1.91V		55		
width				2.01V		55		
				2.31V		55		
				2.51V		55		mV
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unknown state	LVUKS		• See Fig. 8. (Note 8-4)			0.7	0.95	V
Low voltage detection minimum Width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 9.		0.2			ms

Note8-1: The LVD reset level can be selected out of 7 levels only when the LVD reset function is enabled.

Note8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note8-4: LVD is in an unknown state before transistors start operation.

Consumption Current Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

Parameter	Symbol	Pin/	Conditions			Specif	fication	
Farameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1	 FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal low speed and medium speed RC 	2.7 to 5.5		7.4	13.0	
(Note 9-1) (Note 9-2)			oscillation stopped.Frequency variable RC oscillation stopped.1/1 frequency division ratio	2.7 to 3.6		4.4	8.1	
	IDDOP(2)		 CF1=24MHz external clock System clock set to CF1 side Internal low speed and medium speed RC 	3.0 to 5.5		9.7	16.2	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	3.0 to 3.6		5.3	8.7	
	IDDOP(3)		 FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal low speed and medium speed RC 	2.2 to 5.5		6.6	11.9	
			oscillation stopped.Frequency variable RC oscillation stopped.1/1 frequency division ratio	2.2 to 3.6		4.0	7.4	
	IDDOP(4)		 FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal low speed and medium speed RC 	1.8 to 5.5		2.9	6.5	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	1.8 to 3.6		2.2	4.2	mA
	IDDOP(5)		 CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side 	2.2 to 5.5		1.1	2.5	
			 Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio 	2.2 to 3.6		0.6	1.3	
	IDDOP(6)	-	 FsX'tal=32.768kHz crystal oscillation mode Internal low speed RC oscillation stopped. System clock set to internal medium speed 	1.8 to 5.5		0.6	1.7	
			RC oscillation. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.3	0.9	
	IDDOP(7)		 FsX'tal=32.768kHz crystal oscillation mode Internal low speed and medium speed RC oscillation stopped. 	2.7 to 5.5		5.0	9.1	
			 System clock set to 8MHz with frequency variable RC oscillation 1/1 frequency division ratio 	2.7 to 3.6		3.6	5.8	
	IDDOP(8)		 External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC oscillation. 	1.8 to 5.5		75	370	
			 Internal medium speed RC oscillation sopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio 	1.8 to 3.6		46	192	
	IDDOP(9)		 External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC oscillation. 	5.0		75	176	μA
			Internal medium speed RC oscillation sopped.Frequency variable RC oscillation stopped.	3.3		46	115	
			 1/1 frequency division ratio Ta=-10 to +50°C urrent do not include current that flows 	2.5		35	85	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

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Parameter	Symbol	Pin/	Conditions			Speci	fication	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(10)	V _{DD} 1	 FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal low speed and medium speed RC 	1.8 to 5.5		38	139	
(Note 9-1) (Note 9-2)			 oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio 	1.8 to 3.6		15	66	
	IDDOP(11)	-	FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	5.0		38	101	μA
			Internal low speed and medium speed RC oscillation stopped.	3.3		15	46	
			 Frequency variable RC oscillation stopped. 1/2 frequency division ratio Ta=-10 to +50°C 	2.5		9.0	28	
HALT mode consumption current	IDDHALT(1)	V _{DD} 1	HALT mode FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side	2.7 to 5.5		3.1	5.6	
(Note 9-1) (Note 9-2)			 Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio 	2.7 to 3.6		1.6	2.9	
	IDDHALT(2)		 HALT mode CF1=24MHz external clock System clock set to CF1 side Internal low speed and medium speed RC 	3.0 to 5.5		4.9	8.6	
			 Internation speed and mediant speed no oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio 	3.0 to 3.6		2.3	3.8	
	IDDHALT(3)		HALT mode FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal low speed and medium speed RC	2.2 to 5.5		2.7	5.3	
			 Internation speed and medium speed no oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio 	2.2 to 3.6		1.4	2.6	
	IDDHALT(4)		 HALT mode FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal low speed and medium speed RC 	1.8 to 5.5		1.4	3.5	mA
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	1.8 to 3.6		0.7	1.3	
	IDDHALT(5)		 HALT mode CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side 	2.2 to 5.5		0.7	1.8	
			 System clock set to 4 MR2 side Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio 	2.2 to 3.6		0.3	0.7	
	IDDHALT(6)		HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal low speed RC oscillation stopped.	1.8 to 5.5		0.4	1.1	
			 System clock set to internal medium speed RC oscillation Frequency variable RC oscillation stopped. 1/2 frequency division ratio 	1.8 to 3.6		0.2	0.5	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

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Parameter	Symbol	Pin/	Conditions			Speci	fication	
i arameter	Gymbol	remarks		V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 9-1)	IDDHALT(7)	V _{DD} 1	 HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal low speed and medium speed RC oscillation stopped. 	2.7 to 5.5		1.8	3.5	
(Note 9-2)			System clock set to 8MHz with frequency variable RC oscillation 1/1 frequency division ratio	2.7 to 3.6		1.1	2.0	
	IDDHALT(8)		HALT mode External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC cossillation	1.8 to 5.5		23	260	
			 oscillation. Internal medium speed RC oscillation sopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio 	1.8 to 3.6		13	119	μA
	IDDHALT(9)		HALT mode External FsX'tal and FmCF oscillation stopped. System clock set to internal low speed RC	5.0		23	65	
			oscillation. Internal medium speed RC oscillation sopped. 	3.3		13	35	
			 Frequency variable RC oscillation stopped. 1/1 frequency division ratio Ta=-10 to +50°C 	2.5		9.2	25	
	IDDHALT(10)		 HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal low speed and medium speed RC 	1.8 to 5.5		25	112	
			 Internation speed and medium speed no oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio 	1.8 to 3.6		8.5	56	μA
	IDDHALT(11)	11)	HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	5.0		25	69	
			 Internal low speed and medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 	3.3		8.5	29	
		• 1/2 frequency division ratio • Ta=-10 to +50°C		2.5		4.2	15	
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	1.8 to 5.5		0.04	30	
consumption current			• CF1=V _{DD} or open (External clock mode)	1.8 to 3.6		0.02	21	
(Note 9-1)	IDDHOLD(2)		 HOLD mode CF1=V_{DD} or open (External clock mode) 	5.0		0.04	2.3	
(Note 9-2)			• Ta=-10 to +50°C	3.3		0.02	1.5	
				2.5		0.017	1.2	
	IDDHOLD(3)		 HOLD mode CF1=V_{DD} or open (External clock mode) 	1.8 to 5.5		3.2	35	
			LVD option selected	1.8 to 3.6		2.7	24	
	IDDHOLD(4) HOLD mode			5.0		3.2	6.5	μA
			• CF1=V _{DD} or open (External clock mode)	3.3		2.7	4.5	
			 Ta=-10 to +50°C LVD option selected 	2.5		2.5	4.2	
Timer HOLD	IDDHOLD(5)	V _{DD} 1	Timer HOLD mode	1.8 to 5.5		22	106	
mode			• FsX'tal=32.768 kHz crystal oscillation mode	1.8 to 3.6		7.5	45	
consumption	IDDHOLD(6)	1	Timer HOLD mode	5.0		22	62	
current (Note 9-1)			• FsX'tal=32.768kHz crystal oscillation mode	3.3		7.5	23	
(Note 9-2)			• Ta=-10 to +50°C	2.5		2.9	12	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

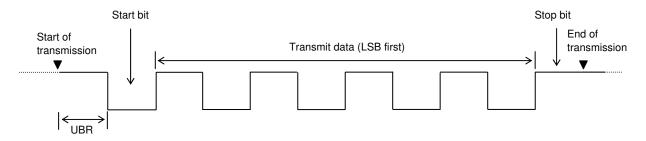
Demension	Symbol Pin/Remarks		Quaditiana			Specification				
Parameter Symbol Pin/		Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Onboard	IDDFW(1)	V _{DD} 1	 Only current of the Flash block. 	0.045.5.5		F	10			
programming current				2.2 to 5.5		5	10	mA		
Programming	tFW(1)		Erasing time	0.0 40 5 5		20	30	ms		
time	tFW(2)		 Programming time 	2.2 to 5.5		40	60	μs		

UART (Full Duplex) Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS1} = V_{SS2} = 0V$

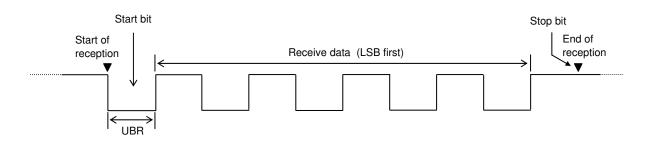
Damantan	Quarte el	Dia (Demonitor				Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Transfer rate	UBR	UTX(P20)		1.8 to 5.5	16/3		8192/3	tCYC		
		URX(P21)		1.6 (0 5.5	10/3		0192/3	1010		
D. (. 1	7/0/01:4	(I CD C								

Data length:7/8/9 bits (LSB first)Stop bits:1 bit (2-bit in continuous data transmission)Parity bits:None

Example of Continuous 8-bit Data Transmission Mode Processing (First Transmit Data=55H)



Example of Continuous 8-bit Data Reception Mode Processing (First Receive Data=55H)



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator • CF oscillation normal amplifier size selected (CFLAMP=0)

■MURATA

Nominal	Nominal Frequency		Circuit Constant				Operating	Oscillation Stabilization Time		
Frequency		Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	1.0k	2.7 to 5.5	0.1	0.5	
	0145	SMD CSTCE10M0G52-R0	(10)	(10)	Open	680	2.2 to 3.6	0.1	0.5	
10MHz	SMD		(10)		Open	1.0k	2.3 to 5.5	0.1	0.5	
	LEAD	CSTLS10M0G53-B0	(15)	(15)	Open	1.0k	2.5 to 5.5	0.1	0.5	
01411-	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	1.5k	2.2 to 5.5	0.1	0.5	
8MHz	LEAD	CSTLS8M00G53-B0	(15)	(15)	Open	1.5k	2.2 to 5.5	0.1	0.5	Internal C1,C2
CMU-	SMD	CSTCR6M00G53-R0	(15)	(15)	Open	2.2k	2.2 to 5.5	0.1	0.5	01,02
6MHz	LEAD	CSTLS6M00G53-B0	(15)	(15)	Open	2.2k	2.2 to 5.5	0.1	0.5	
	0145	CSTCR4M00G53-R0			Open	1.5k	1.8 to 2.7	0.2	0.6	
4MHz	SMD		(15)	(15)	Open	3.3k	1.9 to 5.5	0.2	0.6	
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	3.3k	1.9 to 5.5	0.2	0.6	

• CF oscillation low amplifier size selected (CFLAMP=1)

■MURATA

Nominal Frequency	-		Circuit Constant				Operating	Oscillation Stabilization Time			
	Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	Typ [ms]	Max [ms]	Remarks		
4MHz LEAD			(15)		Open	1.0k	2.1 to 2.7	0.2	0.6		
	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	2.2k	2.5 to 5.5	0.2	0.6		
		CSTCR4M00G53095-R0	(15)	(15)	Open	1.0k	1.9 to 2.7	0.2	0.7	Internal	
				15) (15)	Open	1.0k	2.2 to 2.7	0.2	0.6	C1,C2	
	LEAD	CSTLS4M00G53-B0	(15)		Open	2.2k	2.5 to 5.5	0.2	0.6		
	CSTLS4M00G53095-B0		(15)	(15)	Open	1.0k	2.0 to 2.7	0.2	0.7		

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 3).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator ■EPSON TOYOCOM

Nominal Frequency Type	Ŧ	Oscillator	C	Circuit Cor	nstant		Operating	Oscillation Stabilization Time		Durali
	Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	typ [s]	max [s]	Remarks	
32.768kHz	SMD	MC-306	9	9	Open	330k	1.8 to 5.5	1.4	4.0	Applicable CL value = 7.0pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 3):

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

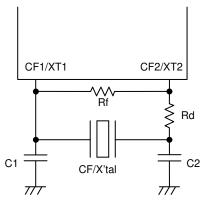


Figure 1 CF and XT Oscillator Circuit

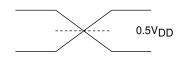
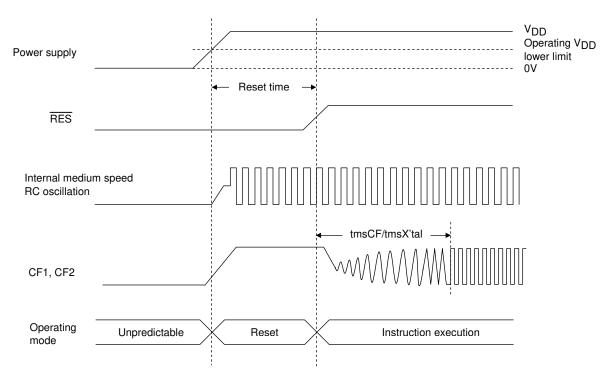
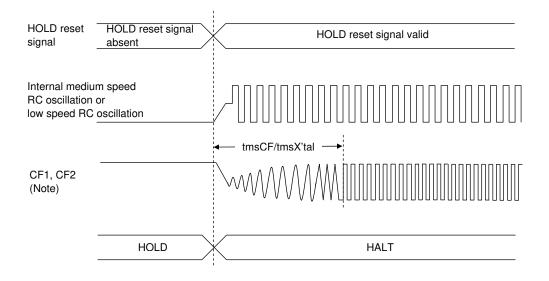


Figure 2 AC Timing Measurement Point



Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Note: External oscillation circuit is selected.

Figure 3 Oscillation Stabilization Times

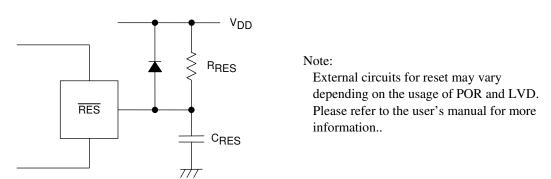


Figure 4 Reset Circuit

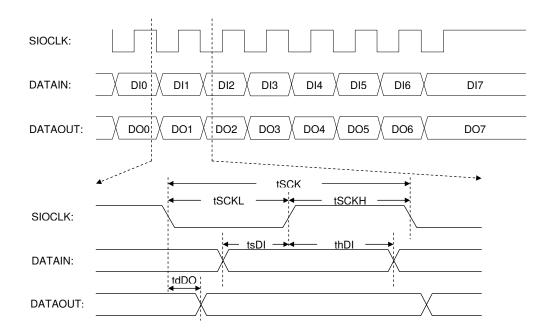


Figure 5 Serial I/O Output Waveforms

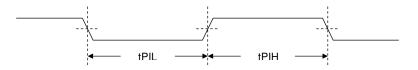


Figure 6 Pulse Input Timing Signal Waveform

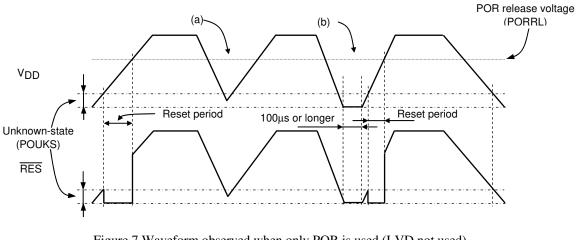


Figure 7 Waveform observed when only POR is used (LVD not used) (RESET pin: Pull-up resistor R_{RES} only)

- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100μ s or longer.

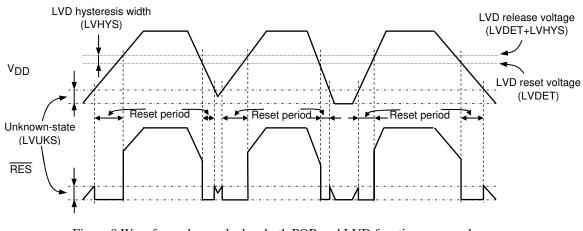


Figure 8 Waveform observed when both POR and LVD functions are used (RESET pin: Pull-up resistor R_{RES} only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

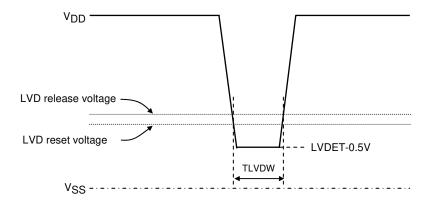


Figure 9 Low voltage detection minimum width (Example of momentary power loss/Voltage variation waveform)

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